**Soracom Announces Commercial Availability of iSIM Technologies and Modules**

Seattle & Tokyo – January 23, 2025 - [Soracom](https://www.soracom.io/), Inc., a global IoT platform provider with full MVNO capability, is pleased to announce the commercial launch of its integrated SIM technology (iSIM) as well as an iSIM-compatible cellular module built off of the Murata Type 1SC. This offering marks Soracom’s third SIM format, with the connectivity solution also offering card-type SIMs as well as chip-type eSIMs, each of which grants users access to Soracom’s best-in-class cellular IoT connectivity platform.

The commercial launch of iSIM technologies has been in the works since July 2021 and has been brought about thanks to key partnerships with IoT chipset developer Sony Semiconductor Israel, Ltd., iSIM module manufacturer Murata, and iSIM Security solutions provider Kigen. Kigen's Secure iSIM Operating System provides robust secure authentication services ensuring reliable out-of-the-box connectivity for commercial iSIM applications.

iSIM technology integrates the functions of the communication module and SIM into a single chip (SoC: System-on-Chip). This enables IoT device manufacturers to create more compact, lightweight and more power-efficient devices, as fewer physical components are required.

Designing connected devices with a single, integrated solution for both the communication module and the SIM reduces procurement, logistics, and storage costs. It also contributes to reduced environmental impact throughout the device manufacturing and sales lifecycle.

“We would like to express our gratitude to our partners for this exciting collaboration. Through this innovative model, iSIM seamlessly connects the LPWA chipset to the Soracom network, simplifying the hardware design and onboarding experience for our customers, said Dima Feldman, VP of Product Management and Marketing, Sony Semiconductor Israel Ltd. “This approach is essential for driving the adoption of lower-power cellular IoT applications and we believe it will significantly enhance IoT device-makers engagement and satisfaction.”

The “Type 1SC” module from Murata Manufacturing Co., Ltd. comes pre-installed with Soracom’s plan01s subscription, allowing users to seamlessly connect to cellular networks worldwide. By utilizing Soracom’s subscription container feature, these modules can access other Soracom data plans, such as the optimized for LPWAN planX3. Regardless of their selected plan, users will also gain access to Soracom’s suite of connectivity tools that cover everything from data and device security to remote provisioning services and cloud integration.

“As an ultra-compact, low-power iSIM-compatible cellular LPWA communication module, our Type 1SC module is a perfect fit for Soracom users,” said Hirokazu Nakae, General Manager, Connectivity Module Product Department, Communication Module Business Unit, Murata Manufacturing Co. Ltd. “Combining our miniaturization technology with iSIM provides users with a quick and easy solution for deploying IoT services at scale.”

“Thanks to our longstanding partnership with Soracom and our ecosystem partners, IoT device manufacturers now have instant access to our iSIM solution, accelerating developers’ speed to market and enhancing their ability to leverage global connectivity,” said Vincent Korstanje, CEO of Kigen. “This is a major milestone in supporting manufacturers with commercial iSIM availability, globally.”

Soracom also offers an evaluation board kit for those customers interested in testing out iSIM integration before committing to a full deployment. This iSIM EVK can handle NTN-IoT services, as well as GNSS.

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About Sony Semiconductor Solutions Corporation

Sony Semiconductor Israel is a leading provider of cellular IoT chipsets. The company’s cellular IoT chipsets are the smallest and most highly integrated LTE CAT-M and NB-IoT chipsets on the market, featuring ultra-low power consumption, hardware-based security, and a carrier-grade integrated SIM (iSIM), all 5G ready. With a commitment to the highest quality and end-to-end security approach, the company’s Altair all-inclusive cellular IoT chipsets offer long battery life and fast time to market.

Sony Semiconductor Israel provides low-power and cost-efficient chipsets for a range of industrial and consumer IoT applications such as trackers, smart meters, smart labels, mHealth, wearables, and vehicle telematics. The company’s cellular IoT chipsets are commercially deployed on the world’s most advanced cellular networks.

About Kigen

Kigen is the forerunner in eSIM and iSIM security-enabled IoT solutions built for scale. An Arm-founded company, Kigen flexibly empowers OEMs with security on leading IoT chipsets and modules and with the world’s leading IoT and LPWAN connectivity providers in up to 200 countries. Our industry-leading SIM OS products enable over 2.5 billion devices and complement our GSMA SAS-accredited Remote SIM provisioning secure service capabilities. Find out more at <https://kigen.com/> or join our #FutureofSIM feed on LinkedIn: <https://linkedin.com/company/kigen/>.

About Murata

Murata Manufacturing Co., Ltd. is a worldwide leader in the design, manufacture and sale of ceramic-based passive electronic components & solutions, communication modules and power supply modules. Murata is committed to the development of advanced electronic materials and leading edge, multi-functional, high-density modules. The company has employees and manufacturing facilities throughout the world. More information is available at [Murata.com](http://murata.com)

About Soracom

Soracom is a technology partner to more than 20,000 startups, SMBs, and enterprises, connecting more than 7 million IoT devices globally. Soracom offers robust solutions specifically designed to make it easy to build, operate, and scale IoT deployments. Customers trust Soracom for affordable, reliable connectivity that accelerates speed to market, makes it easy to connect to any cloud, and offers access to a worldwide partner ecosystem. More information is available at [www.soracom.io](https://cts.businesswire.com/ct/CT?id=smartlink&url=https%3A%2F%2Fwww.soracom.io%2F&esheet=54140733&newsitemid=20241023525336&lan=en-US&anchor=www.soracom.io&index=5&md5=7d98a9b15cd23e8fb9a93c1a5ce3f376)

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